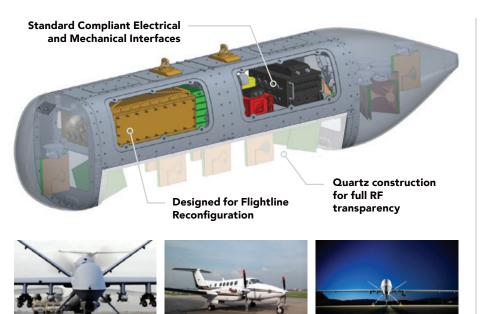
Leidos' Aerial Multi-Mission Pod (AMMP)

ENABLES INTERNAL CONFIGURATION TO FIT THE MISSION REQUIREMENTS AND THE PLATFORM



System Tailoring & Open System Architecture Integration



Onboard Processing:

- Facilitates OA Discovery of Sensor Systems
- Enables Processing at the "Point of Collection"
- Processed Intelligence Delivery at the Tactical Edge
- Reduces Reachback Bandwidth, Data Requirements/Signatures

Leidos is the industry leader for system integration and in the application of open architectures and open standards. Demonstrated through multiple flight test programs, Leidos developed and demonstrated integration of advanced airborne sensors utilizing open architectures. This integration enables collection capabilities to be chosen based on the mission need, rather than on their relationship to other proprietary host platform components. The Leidos Aerial Multi-Mission Pod (AMMP) provides:

- Non-proprietary, Government-owned interfaces; Future Capability Airborne Environment (FACE), Sensor Open Systems Architecture (SOSA), Open Mission Systems (OMS), Modular Open RF Architecture (MORA), SAE International Sensor/ Platform Interface and Engineering Standards (SPIES), the OpenVPX standard, and Vehicular Integration for C4ISR/EW Interoperability (VICTORY)
- Maximum leveraging of the Air Force Research Lab (AFRL) investment in Sensors, Analysis, Integration, Test (SAIT) and Agile Programs
- Maximum use of Commercial-Off-The-Shelf (COTS) components, reducing development schedule
- Modular and scalable integration of legacy and future sensors/capabilities

- Fully supports spiral sensor development
- Multi-Level Security and Cross Domain capable
- Integrates onto multiple manned and unmanned platforms
- Modular and scalable integration of sensors to meet mission requirements
- ► Flight line reconfigurable by organic military personnel
- Standard Electrical and Mechanical interfaces complement the Open Architecture environment
- Reduced development, sustainment and life cycle costs; affordable obsolescence support
- Lightweight composite construction





LEIDOS SOLUTION

Intelligence, Surveillance, and Reconnaissance (ISR) pods are often designed as a point solution for a specific sensor or suite and are often specific to an aircraft. The AMMP's sectional design enables the user to create the right pod configuration to fit the mission sensor requirement. Internal sections and interfaces are designed to fit standards-based Class 1 and Class 2 turreted sensors, antennas, and communications equipment. The sections can be easily configured to create the right pod for the mission. The AMMP mounts to the aircraft using a standard aircraft interface (such as various Bomb Release Unit [BRU] mounting) enabling carriage on a wide variety of aircraft. The AMMP carbon fiber and quartz construction provide significant weight savings over traditional aluminum construction thereby providing greater mission and sensor configuration versatility.

- Government Right to Technical Data
 - Reconfigurable by organic Military Manpower vs. Original Equipment Manufacturer (OEM)/Depot
 - Component Line Replaceable Unit (LRU) vs. Pod as LRU
- Enables Enterprise Solution for Integrated Mission Command Family of Systems
- Meets Army G2 Intent of maximizing use of Unmanned Aircraft System (UAS) ISR vs. Manned ISR
 - Meets Army Requirement to collect intelligence at the speed of mission command
- Leverages large Department of Defense (DoD) Research and Development (R&D) investment to date
 - > Meets Requirement for MQ-1C/MQ-9 Class Pod

ABOUT LEIDOS

Leidos is a Fortune 500[®] information technology, engineering, and science solutions and services leader working to solve the world's toughest challenges in the defense, intelligence, homeland security, civil, and health markets. The company's 32,000 employees support vital missions for government and commercial customers. Headquartered in Reston, Virginia, Leidos reported annual revenues of approximately \$10.19 billion for the fiscal year ended December 28, 2018. For more information, visit www.leidos.com.



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